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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	10 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	8
Number of Macrocells	128
Number of Gates	2500
Number of I/O	84
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm7128stc100-10

- Additional design entry and simulation support provided by EDIF 2.0.0 and 3.0.0 netlist files, library of parameterized modules (LPM), Verilog HDL, VHDL, and other interfaces to popular EDA tools from manufacturers such as Cadence, Exemplar Logic, Mentor Graphics, OrCAD, Synopsys, and VeriBest
- Programming support
 - Altera's Master Programming Unit (MPU) and programming hardware from third-party manufacturers program all MAX 7000 devices
 - The BitBlaster™ serial download cable, ByteBlasterMV™ parallel port download cable, and MasterBlaster™ serial/universal serial bus (USB) download cable program MAX 7000S devices

General Description

The MAX 7000 family of high-density, high-performance PLDs is based on Altera's second-generation MAX architecture. Fabricated with advanced CMOS technology, the EEPROM-based MAX 7000 family provides 600 to 5,000 usable gates, ISP, pin-to-pin delays as fast as 5 ns, and counter speeds of up to 175.4 MHz. MAX 7000S devices in the -5, -6, -7, and -10 speed grades as well as MAX 7000 and MAX 7000E devices in -5, -6, -7, -10P, and -12P speed grades comply with the PCI Special Interest Group (PCI SIG) *PCI Local Bus Specification, Revision 2.2*. See [Table 3](#) for available speed grades.

Table 3. MAX 7000 Speed Grades

Device	Speed Grade									
	-5	-6	-7	-10P	-10	-12P	-12	-15	-15T	-20
EPM7032		✓	✓		✓		✓	✓	✓	
EPM7032S	✓	✓	✓		✓					
EPM7064		✓	✓		✓		✓	✓		
EPM7064S	✓	✓	✓		✓					
EPM7096			✓		✓		✓	✓		
EPM7128E			✓	✓	✓		✓	✓		✓
EPM7128S		✓	✓		✓			✓		
EPM7160E				✓	✓		✓	✓		✓
EPM7160S		✓	✓		✓			✓		
EPM7192E						✓	✓	✓		✓
EPM7192S			✓		✓			✓		
EPM7256E						✓	✓	✓		✓
EPM7256S			✓		✓			✓		

The MAX 7000 architecture supports 100% TTL emulation and high-density integration of SSI, MSI, and LSI logic functions. The MAX 7000 architecture easily integrates multiple devices ranging from PALs, GALs, and 22V10s to MACH and pLSI devices. MAX 7000 devices are available in a wide range of packages, including PLCC, PGA, PQFP, RQFP, and TQFP packages. See [Table 5](#).

Table 5. MAX 7000 Maximum User I/O Pins *Note (1)*

Device	44-Pin PLCC	44-Pin PQFP	44-Pin TQFP	68-Pin PLCC	84-Pin PLCC	100-Pin PQFP	100-Pin TQFP	160-Pin PQFP	160-Pin PGA	192-Pin PGA	208-Pin PQFP	208-Pin RQFP
EPM7032	36	36	36									
EPM7032S	36		36									
EPM7064	36		36	52	68	68						
EPM7064S	36		36		68	68						
EPM7096				52	64	76						
EPM7128E					68	84		100				
EPM7128S					68	84	84 (2)	100				
EPM7160E					64	84		104				
EPM7160S					64		84 (2)	104				
EPM7192E								124	124			
EPM7192S								124				
EPM7256E								132 (2)		164		164
EPM7256S											164 (2)	164

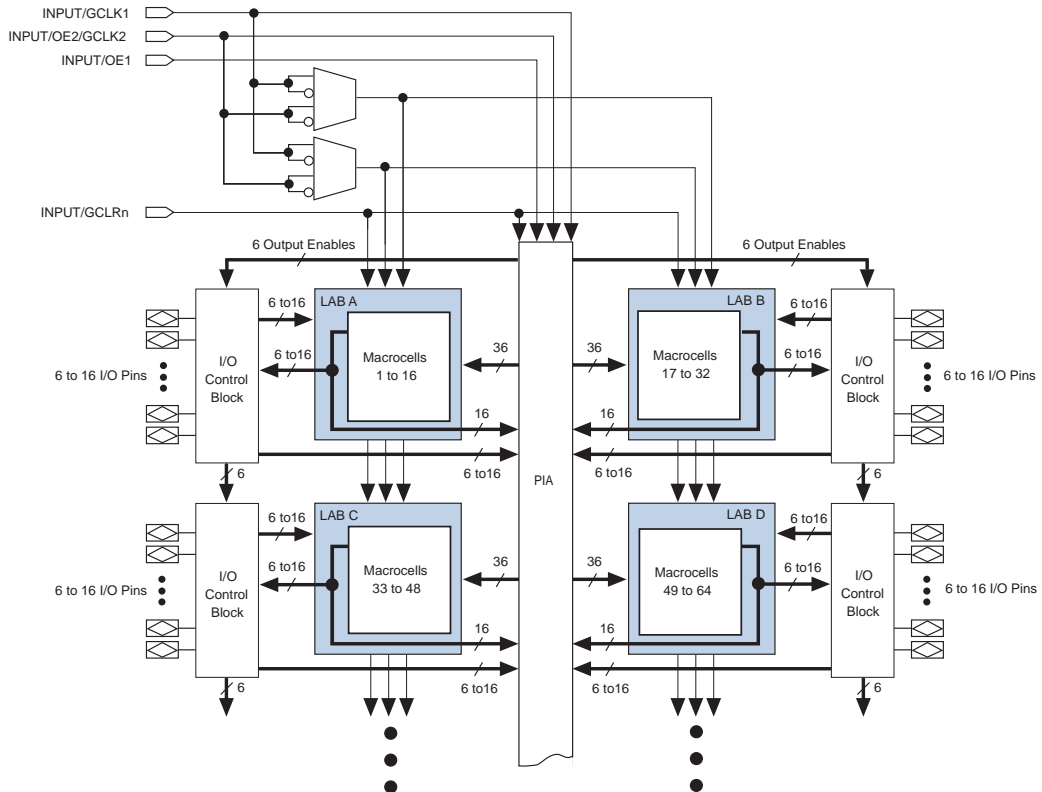
Notes:

- (1) When the JTAG interface in MAX 7000S devices is used for either boundary-scan testing or for ISP, four I/O pins become JTAG pins.
- (2) Perform a complete thermal analysis before committing a design to this device package. For more information, see the [Operating Requirements for Altera Devices Data Sheet](#).

MAX 7000 devices use CMOS EEPROM cells to implement logic functions. The user-configurable MAX 7000 architecture accommodates a variety of independent combinatorial and sequential logic functions. The devices can be reprogrammed for quick and efficient iterations during design development and debug cycles, and can be programmed and erased up to 100 times.

Figure 2 shows the architecture of MAX 7000E and MAX 7000S devices.

Figure 2. MAX 7000E & MAX 7000S Device Block Diagram



Logic Array Blocks

The MAX 7000 device architecture is based on the linking of high-performance, flexible, logic array modules called logic array blocks (LABs). LABs consist of 16-macrocell arrays, as shown in Figures 1 and 2. Multiple LABs are linked together via the programmable interconnect array (PIA), a global bus that is fed by all dedicated inputs, I/O pins, and macrocells.

Each LAB is fed by the following signals:

- 36 signals from the PIA that are used for general logic inputs
- Global controls that are used for secondary register functions
- Direct input paths from I/O pins to the registers that are used for fast setup times for MAX 7000E and MAX 7000S devices

Macrocells

The MAX 7000 macrocell can be individually configured for either sequential or combinatorial logic operation. The macrocell consists of three functional blocks: the logic array, the product-term select matrix, and the programmable register. The macrocell of EPM7032, EPM7064, and EPM7096 devices is shown in Figure 3.

Figure 3. EPM7032, EPM7064 & EPM7096 Device Macrocell

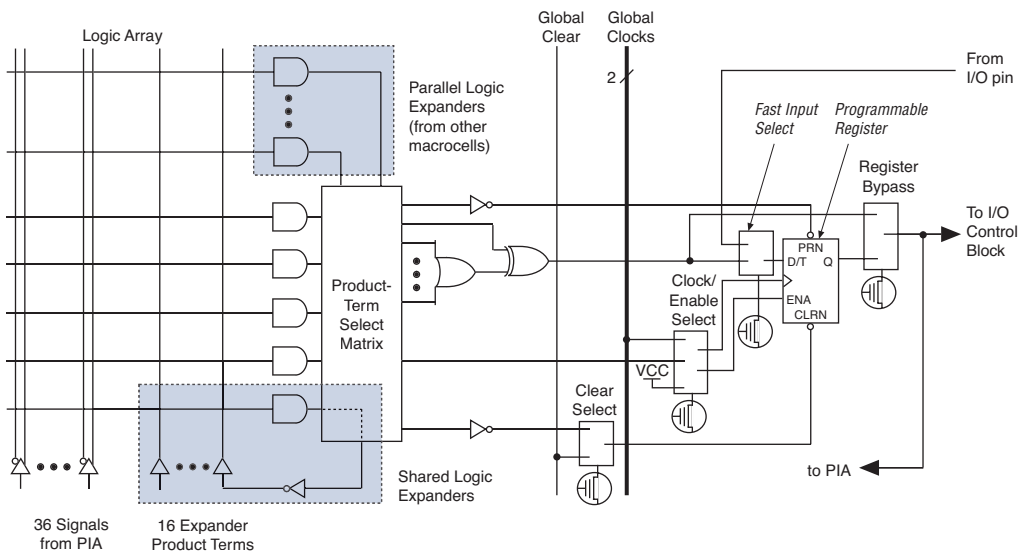
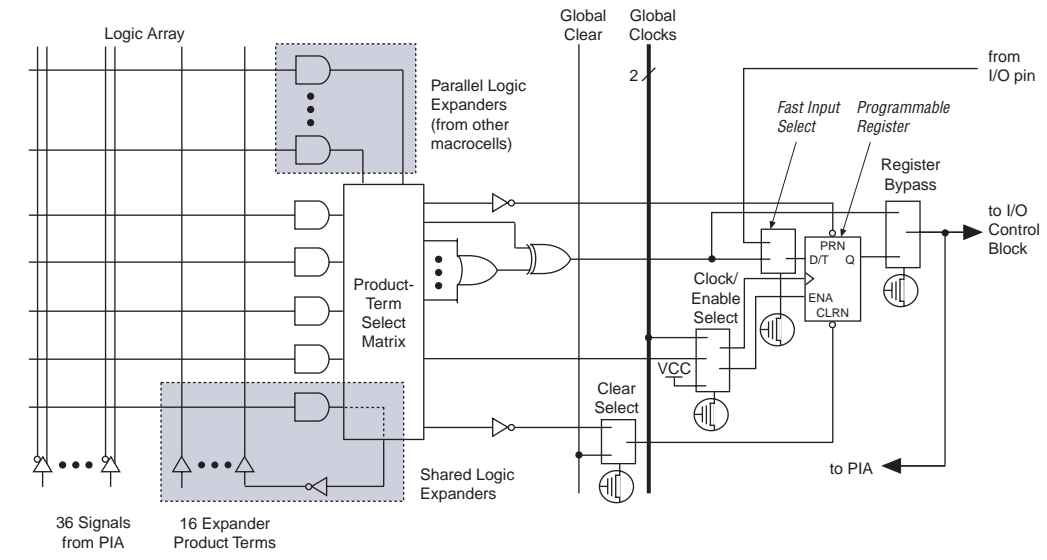


Figure 4 shows a MAX 7000E and MAX 7000S device macrocell.

Figure 4. MAX 7000E & MAX 7000S Device Macrocell



Combinatorial logic is implemented in the logic array, which provides five product terms per macrocell. The product-term select matrix allocates these product terms for use as either primary logic inputs (to the OR and XOR gates) to implement combinatorial functions, or as secondary inputs to the macrocell's register clear, preset, clock, and clock enable control functions. Two kinds of expander product terms ("expanders") are available to supplement macrocell logic resources:

- Shareable expanders, which are inverted product terms that are fed back into the logic array
- Parallel expanders, which are product terms borrowed from adjacent macrocells

The Altera development system automatically optimizes product-term allocation according to the logic requirements of the design.

For registered functions, each macrocell flipflop can be individually programmed to implement D, T, JK, or SR operation with programmable clock control. The flipflop can be bypassed for combinatorial operation. During design entry, the designer specifies the desired flipflop type; the Altera development software then selects the most efficient flipflop operation for each registered function to optimize resource utilization.

The programming times described in [Tables 6 through 8](#) are associated with the worst-case method using the enhanced ISP algorithm.

Table 6. MAX 7000S t_{PULSE} & $Cycle_{TCK}$ Values

Device	Programming		Stand-Alone Verification	
	t_{PULSE} (s)	$Cycle_{PTCK}$	t_{VPULSE} (s)	$Cycle_{VTCK}$
EPM7032S	4.02	342,000	0.03	200,000
EPM7064S	4.50	504,000	0.03	308,000
EPM7128S	5.11	832,000	0.03	528,000
EPM7160S	5.35	1,001,000	0.03	640,000
EPM7192S	5.71	1,192,000	0.03	764,000
EPM7256S	6.43	1,603,000	0.03	1,024,000

[Tables 7 and 8](#) show the in-system programming and stand alone verification times for several common test clock frequencies.

Table 7. MAX 7000S In-System Programming Times for Different Test Clock Frequencies

Device	f_{TCK}								Units
	10 MHz	5 MHz	2 MHz	1 MHz	500 kHz	200 kHz	100 kHz	50 kHz	
EPM7032S	4.06	4.09	4.19	4.36	4.71	5.73	7.44	10.86	s
EPM7064S	4.55	4.60	4.76	5.01	5.51	7.02	9.54	14.58	s
EPM7128S	5.19	5.27	5.52	5.94	6.77	9.27	13.43	21.75	s
EPM7160S	5.45	5.55	5.85	6.35	7.35	10.35	15.36	25.37	s
EPM7192S	5.83	5.95	6.30	6.90	8.09	11.67	17.63	29.55	s
EPM7256S	6.59	6.75	7.23	8.03	9.64	14.45	22.46	38.49	s

Table 8. MAX 7000S Stand-Alone Verification Times for Different Test Clock Frequencies

Device	f_{TCK}								Units
	10 MHz	5 MHz	2 MHz	1 MHz	500 kHz	200 kHz	100 kHz	50 kHz	
EPM7032S	0.05	0.07	0.13	0.23	0.43	1.03	2.03	4.03	s
EPM7064S	0.06	0.09	0.18	0.34	0.64	1.57	3.11	6.19	s
EPM7128S	0.08	0.14	0.29	0.56	1.09	2.67	5.31	10.59	s
EPM7160S	0.09	0.16	0.35	0.67	1.31	3.23	6.43	12.83	s
EPM7192S	0.11	0.18	0.41	0.79	1.56	3.85	7.67	15.31	s
EPM7256S	0.13	0.24	0.54	1.06	2.08	5.15	10.27	20.51	s

By using an external 5.0-V pull-up resistor, output pins on MAX 7000S devices can be set to meet 5.0-V CMOS input voltages. When V_{CCIO} is 3.3 V, setting the open drain option will turn off the output pull-up transistor, allowing the external pull-up resistor to pull the output high enough to meet 5.0-V CMOS input voltages. When V_{CCIO} is 5.0 V, setting the output drain option is not necessary because the pull-up transistor will already turn off when the pin exceeds approximately 3.8 V, allowing the external pull-up resistor to pull the output high enough to meet 5.0-V CMOS input voltages.

Slew-Rate Control

The output buffer for each MAX 7000E and MAX 7000S I/O pin has an adjustable output slew rate that can be configured for low-noise or high-speed performance. A faster slew rate provides high-speed transitions for high-performance systems. However, these fast transitions may introduce noise transients into the system. A slow slew rate reduces system noise, but adds a nominal delay of 4 to 5 ns. In MAX 7000E devices, when the Turbo Bit is turned off, the slew rate is set for low noise performance. For MAX 7000S devices, each I/O pin has an individual EEPROM bit that controls the slew rate, allowing designers to specify the slew rate on a pin-by-pin basis.

Programming with External Hardware

MAX 7000 devices can be programmed on Windows-based PCs with the Altera Logic Programmer card, the Master Programming Unit (MPU), and the appropriate device adapter. The MPU performs a continuity check to ensure adequate electrical contact between the adapter and the device.



For more information, see the [*Altera Programming Hardware Data Sheet*](#).

The Altera development system can use text- or waveform-format test vectors created with the Text Editor or Waveform Editor to test the programmed device. For added design verification, designers can perform functional testing to compare the functional behavior of a MAX 7000 device with the results of simulation. Moreover, Data I/O, BP Microsystems, and other programming hardware manufacturers also provide programming support for Altera devices.



For more information, see the [*Programming Hardware Manufacturers*](#).

IEEE Std. 1149.1 (JTAG) Boundary-Scan Support

MAX 7000 devices support JTAG BST circuitry as specified by IEEE Std. 1149.1-1990. [Table 9](#) describes the JTAG instructions supported by the MAX 7000 family. The pin-out tables (see the Altera web site (<http://www.altera.com>) or the *Altera Digital Library* for pin-out information) show the location of the JTAG control pins for each device. If the JTAG interface is not required, the JTAG pins are available as user I/O pins.

Table 9. MAX 7000 JTAG Instructions

JTAG Instruction	Devices	Description
SAMPLE/PRELOAD	EPM7128S EPM7160S EPM7192S EPM7256S	Allows a snapshot of signals at the device pins to be captured and examined during normal device operation, and permits an initial data pattern output at the device pins.
EXTEST	EPM7128S EPM7160S EPM7192S EPM7256S	Allows the external circuitry and board-level interconnections to be tested by forcing a test pattern at the output pins and capturing test results at the input pins.
BYPASS	EPM7032S EPM7064S EPM7128S EPM7160S EPM7192S EPM7256S	Places the 1-bit bypass register between the TDI and TDO pins, which allows the BST data to pass synchronously through a selected device to adjacent devices during normal device operation.
IDCODE	EPM7032S EPM7064S EPM7128S EPM7160S EPM7192S EPM7256S	Selects the IDCODE register and places it between TDI and TDO, allowing the IDCODE to be serially shifted out of TDO.
ISP Instructions	EPM7032S EPM7064S EPM7128S EPM7160S EPM7192S EPM7256S	These instructions are used when programming MAX 7000S devices via the JTAG ports with the MasterBlaster, ByteBlasterMV, BitBlaster download cable, or using a Jam File (.jam), Jam Byte-Code file (.jbc), or Serial Vector Format file (.svf) via an embedded processor or test equipment.

Figure 13. Switching Waveforms

t_R & $t_F < 3$ ns.
Inputs are driven at 3 V
for a logic high and 0 V
for a logic low. All timing
characteristics are
measured at 1.5 V.

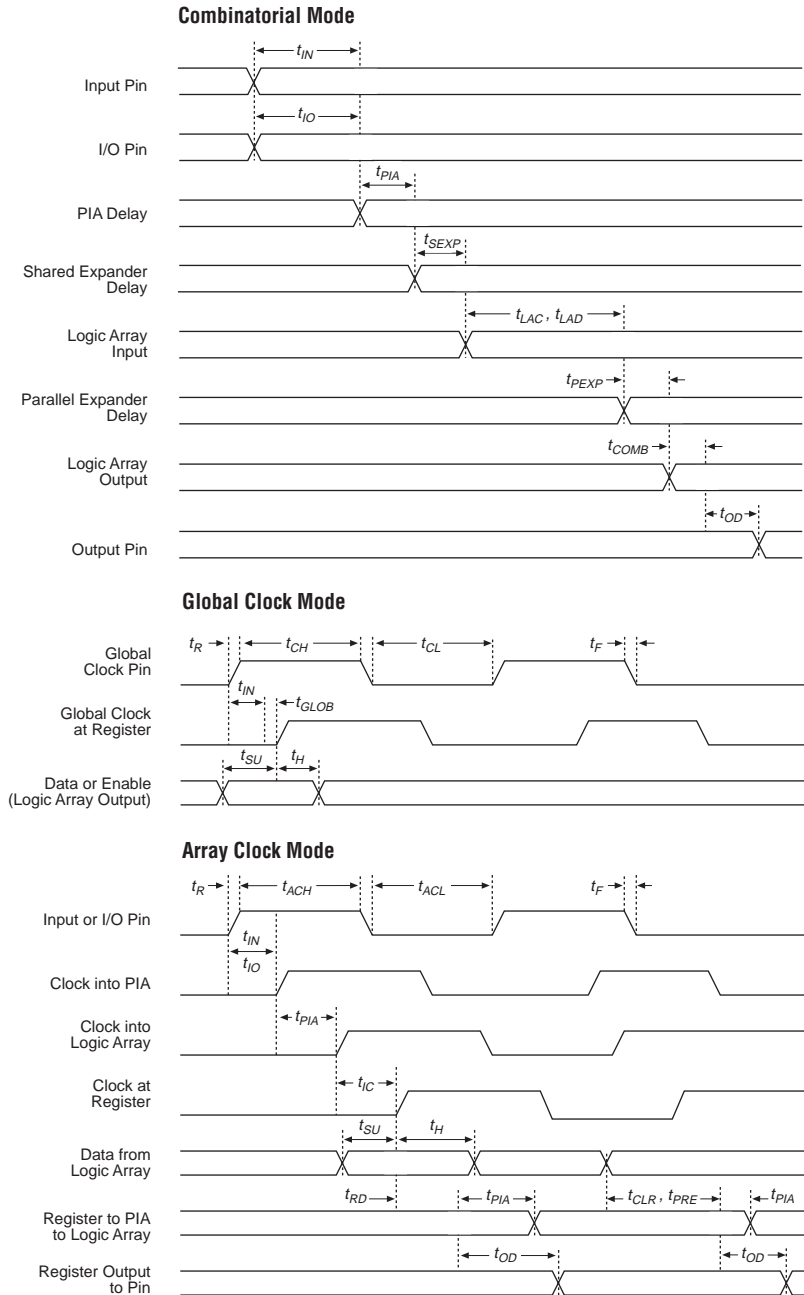


Table 23. MAX 7000 & MAX 7000E External Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade				Unit
			MAX 7000E (-12P)		MAX 7000 (-12) MAX 7000E (-12)		
			Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF		12.0		12.0	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		12.0		12.0	ns
t _{SU}	Global clock setup time		7.0		10.0		ns
t _H	Global clock hold time		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input	(2)	3.0		3.0		ns
t _{FH}	Global clock hold time of fast input	(2)	0.0		0.0		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		6.0		6.0	ns
t _{CH}	Global clock high time		4.0		4.0		ns
t _{CL}	Global clock low time		4.0		4.0		ns
t _{ASU}	Array clock setup time		3.0		4.0		ns
t _{AH}	Array clock hold time		4.0		4.0		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF		12.0		12.0	ns
t _{ACH}	Array clock high time		5.0		5.0		ns
t _{ACL}	Array clock low time		5.0		5.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(3)	5.0		5.0		ns
t _{ODH}	Output data hold time after clock	C1 = 35 pF (4)	1.0		1.0		ns
t _{CNT}	Minimum global clock period			11.0		11.0	ns
f _{CNT}	Maximum internal global clock frequency	(5)	90.9		90.9		MHz
t _{ACNT}	Minimum array clock period			11.0		11.0	ns
f _{ACNT}	Maximum internal array clock frequency	(5)	90.9		90.9		MHz
f _{MAX}	Maximum clock frequency	(6)	125.0		125.0		MHz

Table 25. MAX 7000 & MAX 7000E External Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-15		-15T		-20		
			Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF		15.0		15.0		20.0	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		15.0		15.0		20.0	ns
t _{SU}	Global clock setup time		11.0		11.0		12.0		ns
t _H	Global clock hold time		0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input	(2)	3.0		–		5.0		ns
t _{FH}	Global clock hold time of fast input	(2)	0.0		–		0.0		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		8.0		8.0		12.0	ns
t _{CH}	Global clock high time		5.0		6.0		6.0		ns
t _{CL}	Global clock low time		5.0		6.0		6.0		ns
t _{ASU}	Array clock setup time		4.0		4.0		5.0		ns
t _{AH}	Array clock hold time		4.0		4.0		5.0		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF		15.0		15.0		20.0	ns
t _{ACH}	Array clock high time		6.0		6.5		8.0		ns
t _{ACL}	Array clock low time		6.0		6.5		8.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(3)	6.0		6.5		8.0		ns
t _{ODH}	Output data hold time after clock	C1 = 35 pF (4)	1.0		1.0		1.0		ns
t _{CNT}	Minimum global clock period			13.0		13.0		16.0	ns
f _{CNT}	Maximum internal global clock frequency	(5)	76.9		76.9		62.5		MHz
t _{ACNT}	Minimum array clock period			13.0		13.0		16.0	ns
f _{ACNT}	Maximum internal array clock frequency	(5)	76.9		76.9		62.5		MHz
f _{MAX}	Maximum clock frequency	(6)	100		83.3		83.3		MHz

Notes to tables:

- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This parameter applies to MAX 7000E devices only.
- (3) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (4) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (5) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (6) The f_{MAX} values represent the highest frequency for pipelined data.
- (7) Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , t_{ACL} , and t_{CPPW} parameters for macrocells running in the low-power mode.

Tables 27 and 28 show the EPM7032S AC operating conditions.

Table 27. EPM7032S External Timing Parameters (Part 1 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-5		-6		-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns
t _{SU}	Global clock setup time		2.9		4.0		5.0		7.0		ns
t _H	Global clock hold time		0.0		0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		2.5		2.5		2.5		3.0		ns
t _{FH}	Global clock hold time of fast input		0.0		0.0		0.0		0.5		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		3.2		3.5		4.3		5.0	ns
t _{CH}	Global clock high time		2.0		2.5		3.0		4.0		ns
t _{CL}	Global clock low time		2.0		2.5		3.0		4.0		ns
t _{ASU}	Array clock setup time		0.7		0.9		1.1		2.0		ns
t _{AH}	Array clock hold time		1.8		2.1		2.7		3.0		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF		5.4		6.6		8.2		10.0	ns
t _{ACH}	Array clock high time		2.5		2.5		3.0		4.0		ns
t _{ACL}	Array clock low time		2.5		2.5		3.0		4.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(2)	2.5		2.5		3.0		4.0		ns
t _{ODH}	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns
t _{CNT}	Minimum global clock period			5.7		7.0		8.6		10.0	ns
f _{CNT}	Maximum internal global clock frequency	(4)	175.4		142.9		116.3		100.0		MHz
t _{ACNT}	Minimum array clock period			5.7		7.0		8.6		10.0	ns

Table 29. EPM7064S External Timing Parameters (Part 2 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-5		-6		-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{ACO1}	Array clock to output delay	C1 = 35 pF		5.4		6.7		7.5		10.0	ns
t _{ACH}	Array clock high time		2.5		2.5		3.0		4.0		ns
t _{ACL}	Array clock low time		2.5		2.5		3.0		4.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(2)	2.5		2.5		3.0		4.0		ns
t _{ODH}	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns
t _{CNT}	Minimum global clock period			5.7		7.1		8.0		10.0	ns
f _{CNT}	Maximum internal global clock frequency	(4)	175.4		140.8		125.0		100.0		MHz
t _{ACNT}	Minimum array clock period			5.7		7.1		8.0		10.0	ns
f _{ACNT}	Maximum internal array clock frequency	(4)	175.4		140.8		125.0		100.0		MHz
f _{MAX}	Maximum clock frequency	(5)	250.0		200.0		166.7		125.0		MHz

Table 30. EPM7064S Internal Timing Parameters (Part 1 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-5		-6		-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{IN}	Input pad and buffer delay			0.2		0.2		0.5		0.5	ns
t_{IO}	I/O input pad and buffer delay			0.2		0.2		0.5		0.5	ns
t_{FIN}	Fast input delay			2.2		2.6		1.0		1.0	ns
t_{SEXP}	Shared expander delay			3.1		3.8		4.0		5.0	ns
t_{PEXP}	Parallel expander delay			0.9		1.1		0.8		0.8	ns
t_{LAD}	Logic array delay			2.6		3.2		3.0		5.0	ns
t_{LAC}	Logic control array delay			2.5		3.2		3.0		5.0	ns
t_{IOE}	Internal output enable delay			0.7		0.8		2.0		2.0	ns
t_{OD1}	Output buffer and pad delay	C1 = 35 pF		0.2		0.3		2.0		1.5	ns
t_{OD2}	Output buffer and pad delay	C1 = 35 pF (6)		0.7		0.8		2.5		2.0	ns
t_{OD3}	Output buffer and pad delay	C1 = 35 pF		5.2		5.3		7.0		5.5	ns
t_{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		4.0		4.0		5.0	ns
t_{ZX2}	Output buffer enable delay	C1 = 35 pF (6)		4.5		4.5		4.5		5.5	ns
t_{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		9.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0		4.0		5.0	ns
t_{SU}	Register setup time		0.8		1.0		3.0		2.0		ns
t_H	Register hold time		1.7		2.0		2.0		3.0		ns

Tables 31 and 32 show the EPM7128S AC operating conditions.

Table 31. EPM7128S External Timing Parameters Note (1)											
Symbol	Parameter	Conditions	Speed Grade								Unit
			-6		-7		-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t _{SU}	Global clock setup time		3.4		6.0		7.0		11.0		ns
t _H	Global clock hold time		0.0		0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		2.5		3.0		3.0		3.0		ns
t _{FH}	Global clock hold time of fast input		0.0		0.5		0.5		0.0		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		4.0		4.5		5.0		8.0	ns
t _{CH}	Global clock high time		3.0		3.0		4.0		5.0		ns
t _{CL}	Global clock low time		3.0		3.0		4.0		5.0		ns
t _{ASU}	Array clock setup time		0.9		3.0		2.0		4.0		ns
t _{AH}	Array clock hold time		1.8		2.0		5.0		4.0		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF		6.5		7.5		10.0		15.0	ns
t _{ACH}	Array clock high time		3.0		3.0		4.0		6.0		ns
t _{ACL}	Array clock low time		3.0		3.0		4.0		6.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(2)	3.0		3.0		4.0		6.0		ns
t _{ODH}	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns
t _{CNT}	Minimum global clock period			6.8		8.0		10.0		13.0	ns
f _{CNT}	Maximum internal global clock frequency	(4)	147.1		125.0		100.0		76.9		MHz
t _{ACNT}	Minimum array clock period			6.8		8.0		10.0		13.0	ns
f _{ACNT}	Maximum internal array clock frequency	(4)	147.1		125.0		100.0		76.9		MHz
f _{MAX}	Maximum clock frequency	(5)	166.7		166.7		125.0		100.0		MHz

Table 33. EPM7160S External Timing Parameters (Part 2 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-6		-7		-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{ACNT}	Minimum array clock period			6.7		8.2		10.0		13.0	ns
f _{ACNT}	Maximum internal array clock frequency	(4)	149.3		122.0		100.0		76.9		MHz
f _{MAX}	Maximum clock frequency	(5)	166.7		166.7		125.0		100.0		MHz

Table 34. EPM7160S Internal Timing Parameters (Part 1 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-6		-7		-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{IN}	Input pad and buffer delay			0.2		0.3		0.5		2.0	ns
t_{IO}	I/O input pad and buffer delay			0.2		0.3		0.5		2.0	ns
t_{FIN}	Fast input delay			2.6		3.2		1.0		2.0	ns
t_{SEXP}	Shared expander delay			3.6		4.3		5.0		8.0	ns
t_{PEXP}	Parallel expander delay			1.0		1.3		0.8		1.0	ns
t_{LAD}	Logic array delay			2.8		3.4		5.0		6.0	ns
t_{LAC}	Logic control array delay			2.8		3.4		5.0		6.0	ns
t_{IOE}	Internal output enable delay			0.7		0.9		2.0		3.0	ns
t_{OD1}	Output buffer and pad delay	C1 = 35 pF		0.4		0.5		1.5		4.0	ns
t_{OD2}	Output buffer and pad delay	C1 = 35 pF (6)		0.9		1.0		2.0		5.0	ns
t_{OD3}	Output buffer and pad delay	C1 = 35 pF		5.4		5.5		5.5		8.0	ns
t_{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		4.0		5.0		6.0	ns
t_{ZX2}	Output buffer enable delay	C1 = 35 pF (6)		4.5		4.5		5.5		7.0	ns
t_{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		10.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0		5.0		6.0	ns
t_{SU}	Register setup time		1.0		1.2		2.0		4.0		ns
t_H	Register hold time		1.6		2.0		3.0		4.0		ns
t_{FSU}	Register setup time of fast input		1.9		2.2		3.0		2.0		ns
t_{FH}	Register hold time of fast input		0.6		0.8		0.5		1.0		ns
t_{RD}	Register delay			1.3		1.6		2.0		1.0	ns
t_{COMB}	Combinatorial delay			1.0		1.3		2.0		1.0	ns
t_{IC}	Array clock delay			2.9		3.5		5.0		6.0	ns
t_{EN}	Register enable time			2.8		3.4		5.0		6.0	ns
t_{GLOB}	Global control delay			2.0		2.4		1.0		1.0	ns
t_{PRE}	Register preset time			2.4		3.0		3.0		4.0	ns

Table 34. EPM7160S Internal Timing Parameters (Part 2 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-6		-7		-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{CLR}	Register clear time			2.4		3.0		3.0		4.0	ns
t_{PIA}	PIA delay	(7)		1.6		2.0		1.0		2.0	ns
t_{LPA}	Low-power adder	(8)		11.0		10.0		11.0		13.0	ns

Notes to tables:

- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The f_{MAX} values represent the highest frequency for pipelined data.
- (6) Operating conditions: $V_{CCIO} = 3.3\text{ V} \pm 10\%$ for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , t_{ACL} , and t_{CPPW} parameters for macrocells running in the low-power mode.

Tables 35 and 36 show the EPM7192S AC operating conditions.

Table 35. EPM7192S External Timing Parameters (Part 1 of 2) *Note (1)*

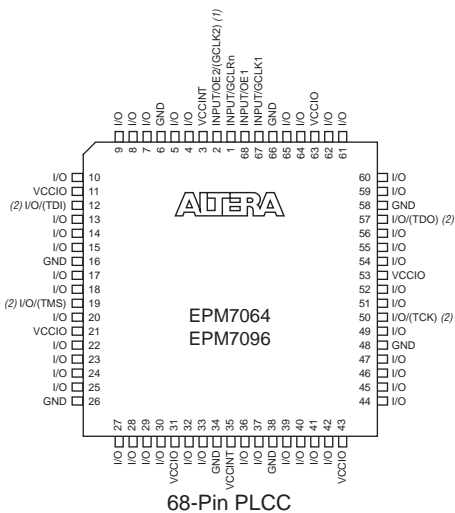
Symbol	Parameter	Conditions	Speed Grade						Unit
			-7		-10		-15		
			Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns
t _{SU}	Global clock setup time		4.1		7.0		11.0		ns
t _H	Global clock hold time		0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		3.0		3.0		3.0		ns
t _{FH}	Global clock hold time of fast input		0.0		0.5		0.0		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		4.7		5.0		8.0	ns
t _{CH}	Global clock high time		3.0		4.0		5.0		ns
t _{CL}	Global clock low time		3.0		4.0		5.0		ns
t _{ASU}	Array clock setup time		1.0		2.0		4.0		ns

Table 35. EPM7192S External Timing Parameters (Part 2 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-7		-10		-15		
			Min	Max	Min	Max	Min	Max	
t _{AH}	Array clock hold time		1.8		3.0		4.0		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF		7.8		10.0		15.0	ns
t _{ACH}	Array clock high time		3.0		4.0		6.0		ns
t _{ACL}	Array clock low time		3.0		4.0		6.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(2)	3.0		4.0		6.0		ns
t _{ODH}	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		ns
t _{CNT}	Minimum global clock period			8.0		10.0		13.0	ns
f _{CNT}	Maximum internal global clock frequency	(4)	125.0		100.0		76.9		MHz
t _{ACNT}	Minimum array clock period			8.0		10.0		13.0	ns
f _{ACNT}	Maximum internal array clock frequency	(4)	125.0		100.0		76.9		MHz
f _{MAX}	Maximum clock frequency	(5)	166.7		125.0		100.0		MHz

Table 36. EPM7192S Internal Timing Parameters (Part 1 of 2) *Note (1)*

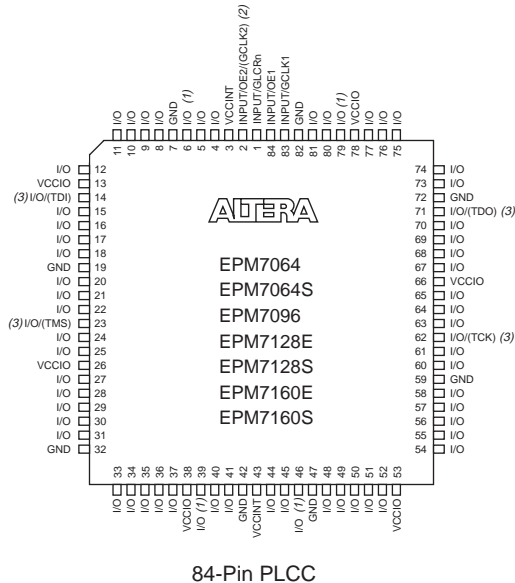
Symbol	Parameter	Conditions	Speed Grade						Unit
			-7		-10		-15		
			Min	Max	Min	Max	Min	Max	
t_{IN}	Input pad and buffer delay			0.3		0.5		2.0	ns
t_{IO}	I/O input pad and buffer delay			0.3		0.5		2.0	ns
t_{FIN}	Fast input delay			3.2		1.0		2.0	ns
t_{SEXP}	Shared expander delay			4.2		5.0		8.0	ns
t_{PEXP}	Parallel expander delay			1.2		0.8		1.0	ns
t_{LAD}	Logic array delay			3.1		5.0		6.0	ns
t_{LAC}	Logic control array delay			3.1		5.0		6.0	ns
t_{IOE}	Internal output enable delay			0.9		2.0		3.0	ns
t_{OD1}	Output buffer and pad delay	C1 = 35 pF		0.5		1.5		4.0	ns
t_{OD2}	Output buffer and pad delay	C1 = 35 pF (6)		1.0		2.0		5.0	ns
t_{OD3}	Output buffer and pad delay	C1 = 35 pF		5.5		5.5		7.0	ns
t_{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		5.0		6.0	ns
t_{ZX2}	Output buffer enable delay	C1 = 35 pF (6)		4.5		5.5		7.0	ns
t_{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		10.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		5.0		6.0	ns
t_{SU}	Register setup time		1.1		2.0		4.0		ns

Figure 17. 68-Pin Package Pin-Out Diagram*Package outlines not drawn to scale.***Notes:**

- (1) The pin functions shown in parenthesis are only available in MAX 7000E and MAX 7000S devices.
- (2) JTAG ports are available in MAX 7000S devices only.

Figure 18. 84-Pin Package Pin-Out Diagram

Package outline not drawn to scale.



Notes:

- (1) Pins 6, 39, 46, and 79 are no-connect (N.C.) pins on EPM7096, EPM7160E, and EPM7160S devices.
- (2) The pin functions shown in parenthesis are only available in MAX 7000E and MAX 7000S devices.
- (3) JTAG ports are available in MAX 7000S devices only.

Revision History

The information contained in the *MAX 7000 Programmable Logic Device Family Data Sheet* version 6.7 supersedes information published in previous versions. The following changes were made in the *MAX 7000 Programmable Logic Device Family Data Sheet* version 6.7:

Version 6.7

The following changes were made in the *MAX 7000 Programmable Logic Device Family Data Sheet* version 6.7:

- Reference to *AN 88: Using the Jam Language for ISP & ICR via an Embedded Processor* has been replaced by *AN 122: Using Jam STAPL for ISP & ICR via an Embedded Processor*.

Version 6.6

The following changes were made in the *MAX 7000 Programmable Logic Device Family Data Sheet* version 6.6:

- Added [Tables 6](#) through [8](#).
- Added “[Programming Sequence](#)” section on [page 17](#) and “[Programming Times](#)” section on [page 18](#).

Version 6.5

The following changes were made in the *MAX 7000 Programmable Logic Device Family Data Sheet* version 6.5:

- Updated text on [page 16](#).

Version 6.4

The following changes were made in the *MAX 7000 Programmable Logic Device Family Data Sheet* version 6.4:

- Added [Note \(5\)](#) on [page 28](#).

Version 6.3

The following changes were made in the *MAX 7000 Programmable Logic Device Family Data Sheet* version 6.3:

- Updated the “[Open-Drain Output Option \(MAX 7000S Devices Only\)](#)” section on [page 20](#).